

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.75 (3.3 EP)
Lead Count	32
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	3.40E-02	83.25	832500	44.46		444570
Thermosets	Epoxy resin	Proprietary	2.22E-03	5.42	54200	2.89		28944
Thermosets	Phenol resin	Proprietary	1.41E-03	3.45	34500	1.84		18424
Other inorganic materials	Metal Hydroxide	Proprietary	2.22E-03	5.42	54200	2.89		28944
Others	Others	Proprietary	1.01E-03	2.46	24600	1.31		13137
Subtotal			4.09E-02	100.00	1000000	53.40		534018

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	3.05 E-02	97.50	975000	39.84		398423
Copper & its alloys	Iron	7439-89-6	7.35 E-04	2.35	23500	0.96		9603
Copper & its alloys	Zinc	7440-66-6	3.75 E-05	0.12	1200	0.05		490
Copper & its alloys	Phosphorus	7723-14-0	9.38 E-06	0.03	300	0.01		123
Subtotal			3.13 E-02	100.00	1000000	40.86		408639

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Nickel & its alloys	Nickel	7440-02-0	3.16 E-04	95.7	956938	0.41		4125
Precious metals	Palladium	7440-05-3	9.47 E-06	2.9	28708	0.01		124
Precious metals	Gold	7440-57-5	4.74 E-06	1.4	14354	0.01		62
Subtotal			3.30 E-04	100.00	1000000	0.43		4311

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	4.95 E-04	100.0	1000000	0.65		6461

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	3.13 E-03	100.0	1000000	4.08		40844

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	3.38 E-04	77.00	770000	0.44		4410
Other organic materials	Acrylic resin	Proprietary	3.07 E-05	7.00	70000	0.04		401
Other organic materials	Acrylate	Proprietary	2.41 E-05	5.50	55000	0.03		315
Other organic materials	Polybutadiene derivative	Proprietary	1.97 E-05	4.50	45000	0.03		258
Thermoset	Epoxy resin	Proprietary	1.10 E-05	2.50	25000	0.01		143
Other organic materials	Butadiene Copolymer	Proprietary	6.58 E-06	1.50	15000	0.01		86
Others	Additive	Proprietary	6.58 E-06	1.50	15000	0.01		86
Others	Peroxide	Proprietary	2.19 E-06	0.50	5000	0.00		29
Subtotal			4.38 E-04	100.0	1000000	0.57		5727

Package Totals			Weight (g)	Percentage (%)	PPM			
			7.66 E-02	100.00	1000000			

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

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Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	4.03E-02	86.2	862000	38.13	381258
Thermosets	Epoxy resin	Proprietary	2.80E-03	6.0	60000	2.65	26538
Thermosets	Phenol resin	Proprietary	2.80E-03	6.0	60000	2.65	26538
Other inorganic materials	Metal Hydroxide	Proprietary	7.01E-04	1.5	15000	0.66	6634
Other inorganic materials	Carbon black	1333-86-4	1.40E-04	0.3	3000	0.13	1327
Subtotal			4.67 E-02	100.00	1000000	44.23	442294

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.95 E-02	97.50	975000	46.89	468896
Copper & its alloys	Iron	7439-89-6	1.19 E-03	2.35	23500	1.13	11302
Copper & its alloys	Zinc	7440-66-6	6.10 E-05	0.12	1200	0.06	577
Copper & its alloys	Phosphorus	7723-14-0	1.52 E-05	0.03	300	0.01	144
Subtotal			5.08 E-02	100.00	1000000	48.09	480919

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.08 E-04	100.0	1000000	0.48	4809

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.96 E-03	100.0	1000000	2.81	28061

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.65 E-04	100.0	1000000	0.54	5352

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.57 E-03	100.0	1000000	3.38	33823

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.68 E-04	73.40	734000	0.35	3480
Thermoset	Epoxy Resin	Proprietary	9.19 E-05	18.35	183500	0.09	870
Other organic materials	Metal oxide	Proprietary	1.38 E-05	2.75	27500	0.01	130
Other organic materials	Amine	Proprietary	1.38 E-05	2.75	27500	0.01	130
Other organic materials	Gamma Butyrolactone	Proprietary	1.38 E-05	2.75	27500	0.01	130
Subtotal			5.01 E-04	100.0	1000000	0.47	4741

Package Totals	Weight (g)	Percentage (%)	PPM
	1.06 E-01	100	1000000

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